

L. Nelson
#4/Pre Amdt. A
4-8-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Beaman et al.

Serial No.: 09/921,867

Filed: August 3, 2001

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS,
TEST PROBE AND METHODS OF USE THEREOF

Date: April 2, 2002

Group Art Unit: 3729

Examiner:

Docket No.: YOR919930028US6

Assistant Commissioner for Patents
Washington, D. C. 20231

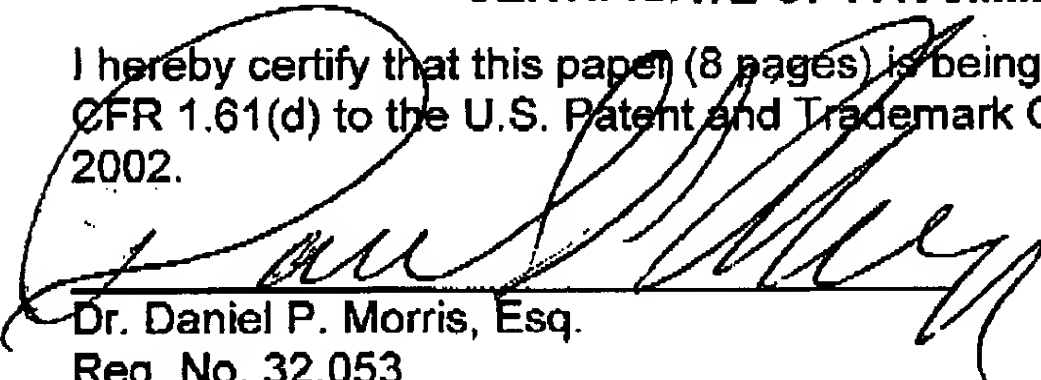
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GROUP 3700

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CFR 1.61(d) to the U.S. Patent and Trademark Office to (703) 872-9302 on April 2,
2002.


Dr. Daniel P. Morris, Esq.
Reg. No. 32,053PRELIMINARY AMENDMENT

IN THE CLAIMS

Cancel claims 1-~~28~~²⁸

Add the following claims:

~~30.~~ (Added) A method of fabricating an electrical interconnection element having a
contact tip structure, comprising:

forming a contact tip structure on a sacrificial substrate;

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